DECLARATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or the below named inventors are the original, first and joint inventors (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR DEVICE AND METHOD FOR LOWERING MILLER CAPACITANCE FOR HIGH-SPEED MICROPROCESSORS, the Specification of which:

	is attached hereto. was filed on	as Application	Serial No.	<u>-</u> ·	
I here including the c	-	iewed and unders	tand the contents	of the above-identified specif	fication
material to pa				ice all information known to m s "materiality" is defined in T	
patent, United any foreign ap	States provisional applica	tion(s), or invento d States provisiona	r's certificate listed	119 of any foreign application below and have also identified wentor's certificate having a filing	d below
	PRIOR	ITY APPLICATI	ON(S)	Priority Claimed	
(Number)	(Country)	(Date Filed)	Yes/No	
(Number)	(Country)	(Date Filed)	Yes/No	
listed below ar United States a acknowledge t claimed in this become availal this application	nd, insofar as the subject in application in the manner the duty to disclose all inful inful in a supplication, as "materiable between the filing date in:	matter of each of the provided by the cormation known to lity" is defined in a of the prior application.	he claims of this apprint paragraph of one to be material Title 37, Code of cation and the nation	O of any United States application is not disclosed in the Fitle 35, United States Code, § to patentability of the subject Federal Regulations, § 1.56, nal or PCT international filing	he prior § 112, I t matter , which
(App	lication Serial No.)	(Filing Date)	(Status	i)	

I hereby direct that all correspondence and telephone calls be addressed to Randall C. Furlong, Ph.D., Williams, Morgan & Amerson, P.C., 7676 Hillmont, Suite 250, Houston, Texas 77040, (713) 934-4061.

(Status)

(Filing Date)

(Application Serial No.)

I HEREBY DECLARE THAT ALL STATEMENTS MADE OF MY OWN KNOWLEDGE ARE TRUE AND THAT ALL STATEMENTS MADE ON INFORMATION AND BELIEF ARE BELIEVED TO BE TRUE; AND FURTHER THAT THESE STATEMENTS WERE MADE WITH THE KNOWLEDGE THAT WILLFUL FALSE STATEMENTS AND THE LIKE SO MADE ARE PUNISHABLE BY FINE OR IMPRISONMENT, OR BOTH, UNDER SECTION 1001 OF TITLE 18 OF THE UNITED STATES CODE AND THAT SUCH WILLFUL FALSE STATEMENTS MAY JEOPARDIZE THE VALIDITY OF THE APPLICATION OR ANY PATENT ISSUED THEREON.

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REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)

First Named Inventor		WU et al	`			
Title	Semiconductor Device and Method					
		2000.032100/TT3632				

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

2/15/2001

Randall C. Furlong, Ph.D.

Typed or printed name

Signature

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**